



## Features

- The PJM7002KNSA uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge.
- Fast switching
- Low gate charge and  $R_{DS(ON)}$
- Low reverse transfer capacitances
- 100% single pulse avalanche energy test
- $V_{DSS}=60V$

$I_D=0.3A$

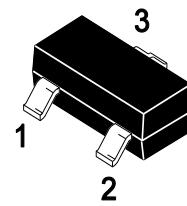
$P_D=0.35W$

$R_{DS(ON)(TYP)}=1\Omega$

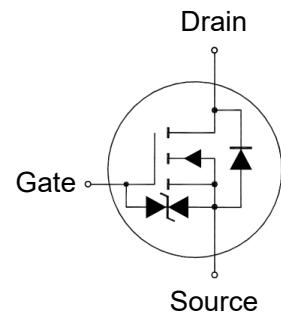
## Applications

- PWM applications
- Load switch
- Power management

SOT-23



1. Gate 2. Source 3. Drain



## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise stated)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	60	V
$I_D$	Continuous Drain Current	0.3	A
	Continuous Drain Current $T_c=100^\circ C$	0.19	A
$I_{DM}^{a1}$	Pulsed Drain Current	0.9	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$V_{ESD}(G-S)$	Gate source ESD (HBM-C= 100pF, $R=1.5k\Omega$ )	2000	V
$dv/dt^{a2}$	Peak Diode Recovery $dv/dt$	5.0	V/ns
$P_D$	Power Dissipation	0.35	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	150 , -55 to 150	$^\circ C$
$T_L$	Maximum Temperature for Soldering	300	$^\circ C$

a1 : Repetitive rating; pulse width limited by maximum junction temperature

a2 :  $I_{SD}=0.3A, dI/dt \leq 100A/\mu s, V_{DD} \leq BV_{DS}$ , Start  $T_J=25^\circ C$



**PJM7002KNSA**  
Single N-Channel Power MOSFET

**Electrical Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise specified)**

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
<b>Off Characteristics</b>						
$V_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu\text{A}, \text{Reference } 25^\circ\text{C}$	--	0.1	--	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS}=60\text{V}, V_{GS}=0\text{V}, T_a=25^\circ\text{C}$	--	--	1	$\mu\text{A}$
		$V_{DS}=48\text{V}, V_{GS}=0\text{V}, T_a=125^\circ\text{C}$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS} = +20\text{V}$	--	--	1	$\mu\text{A}$
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = -20\text{V}$	--	--	-1	$\mu\text{A}$
<b>On Characteristics</b>						
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10\text{V}, I_D=0.5\text{A}$	--	1	1.8	$\Omega$
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=0.3\text{A}$	--	1.2	2.2	$\Omega$
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.7	2.5	V
Pulse width $tp \leq 380\mu\text{s}, \delta \leq 2\%$						
<b>Dynamic Characteristics</b>						
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}, I_D=0.2\text{A}$	0.1	5.0	--	S
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS}=15\text{V}$ $f=1.0\text{MHz}$	--	20	--	pF
$C_{oss}$	Output Capacitance		--	12	--	
$C_{rss}$	Reverse Transfer Capacitance		--	4.4	--	
<b>Resistive Switching Characteristics</b>						
$t_{d(ON)}$	Turn-on Delay Time	$I_D = 0.2\text{A}, V_{DD} = 15\text{V}$ $V_{GS} = 10\text{V},$ $R_G = 3.0\Omega$	--	10	--	ns
$t_r$	Rise Time		--	45	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	15	--	
$t_f$	Fall Time		--	10	--	
$Q_g$	Total Gate Charge	$I_D = 0.3\text{A}, V_{DD} = 15\text{V}, V_{GS} = 10\text{V}$	--	1.7	--	nC
$Q_{gs}$	Gate to Source Charge		--	0.9	--	
$Q_{gd}$	Gate to Drain ("Miller") Charge		--	1.3	--	
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Continuous Source Current (Body Diode)		--	--	0.3	A
$I_{SM}$	Maximum Pulsed Current (Body Diode)		--	--	0.9	A
$V_{SD}$	Diode Forward Voltage	$I_S=0.3\text{A}, V_{GS}=0\text{V}$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_S=0.3\text{A}, T_J= 25^\circ\text{C}$ $dI_F/dt=100\text{A/us}, V_{GS}=0\text{V}$	--	40	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	120	--	nC
Pulse width $tp \leq 380\mu\text{s}, \delta \leq 2\%$						

Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	350	$^\circ\text{C/W}$



## Typical Characteristic Curves

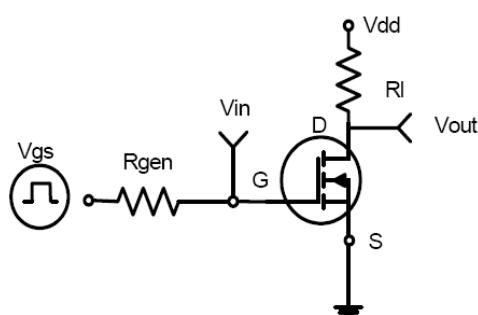


Figure 1:Switching Test Circuit

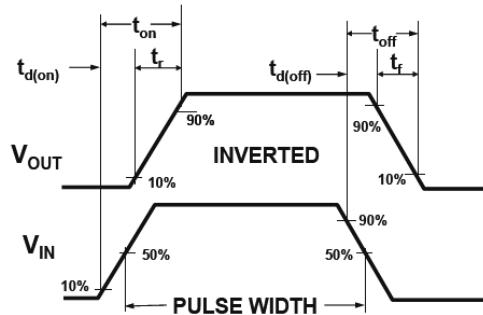


Figure 2:Switching Waveforms

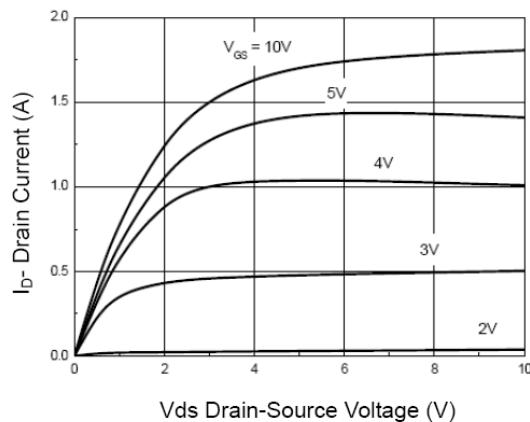


Figure 3 Output Characteristics

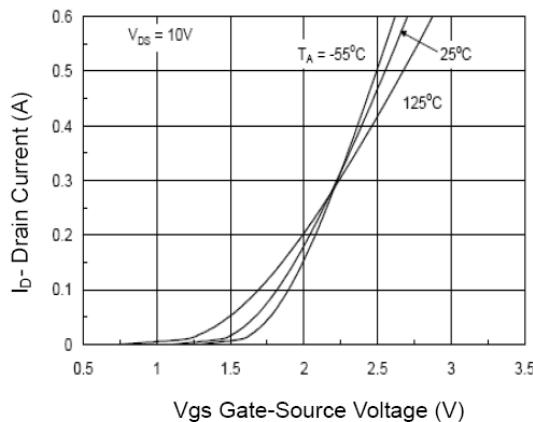


Figure 4 Transfer Characteristics

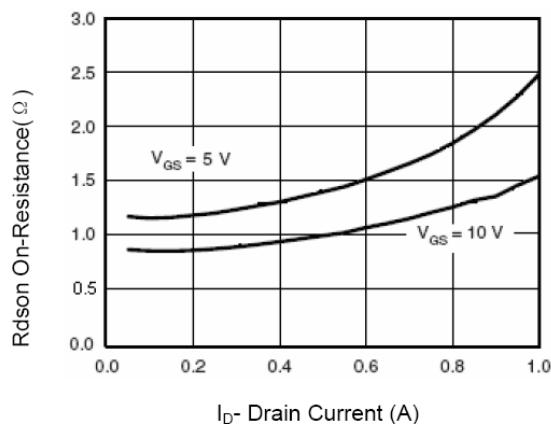


Figure 5 Drain-Source On-Resistance

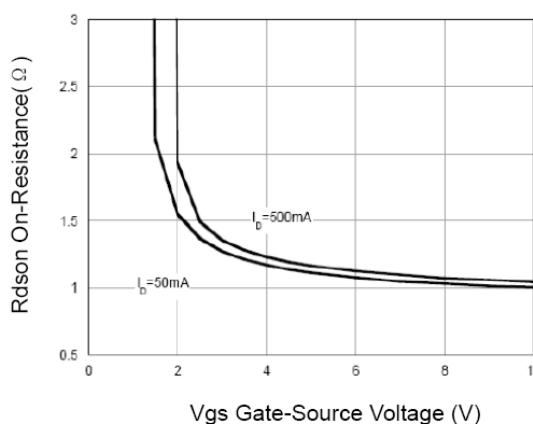
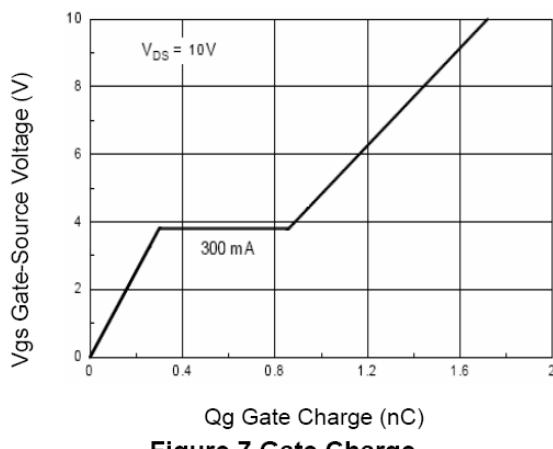
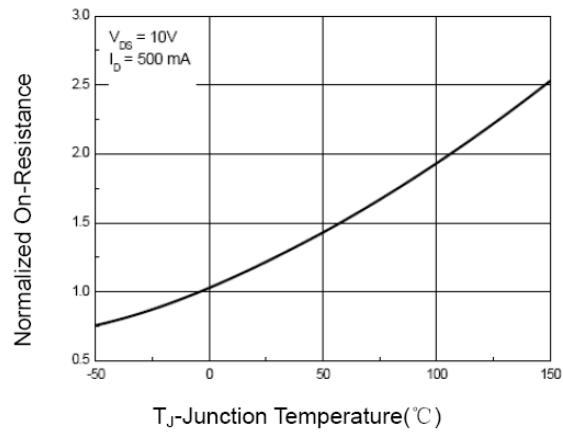


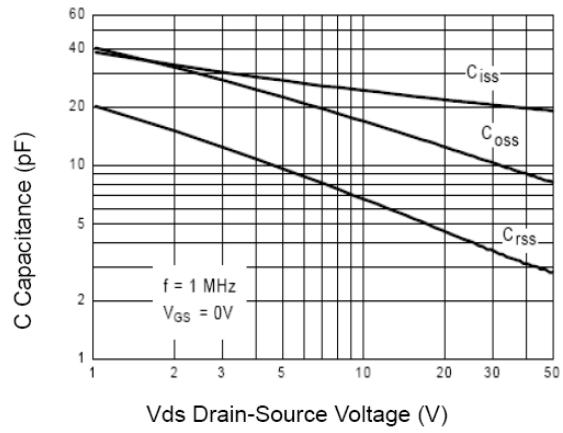
Figure 6 Rdson vs Vgs



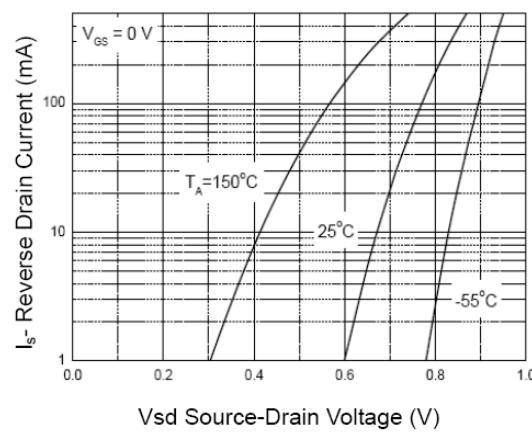
**Figure 7 Gate Charge**



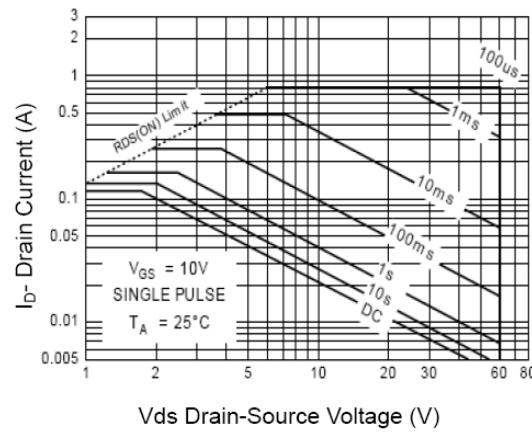
**Figure 9 Drain-Source On-Resistance**



**Figure 11 Capacitance vs Vds**



**Figure 8 Source-DrainDiode Forward**



**Figure 10 Safe Operation Area**

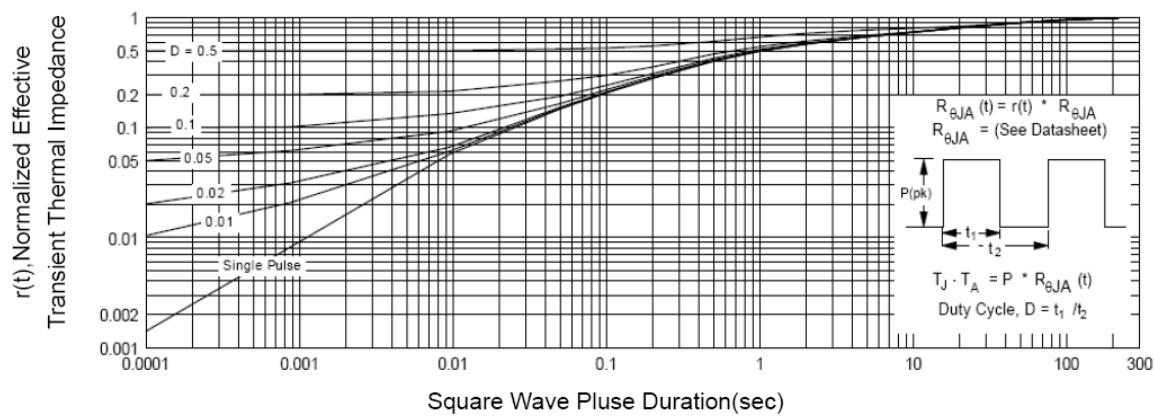
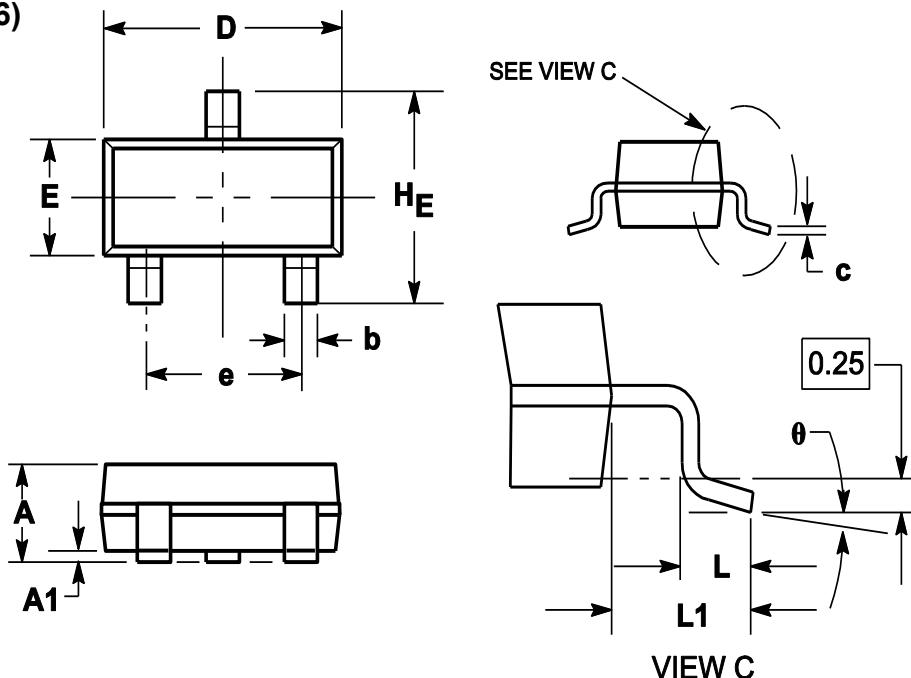


Figure 12 Normalized Maximum Transient Thermal Impedance

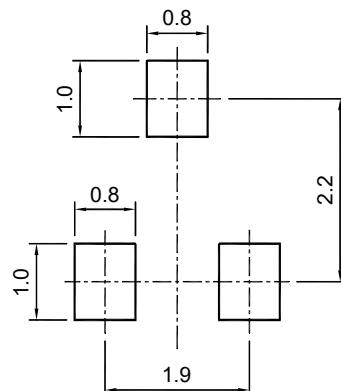


## Package Outline

SOT-23 (TO-236)



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
HE	2.250	2.400	2.550
e	1.800	1.900	2.000
L1	0.550REF		
L	0.300		0.500
θ	0°		8°



SOT-23 (TO-236)

Recommended soldering pad

## Ordering information

Device	Package	Shipping
PJM7002KNSA	SOT-23	3000/Reel&Tape(7inch)